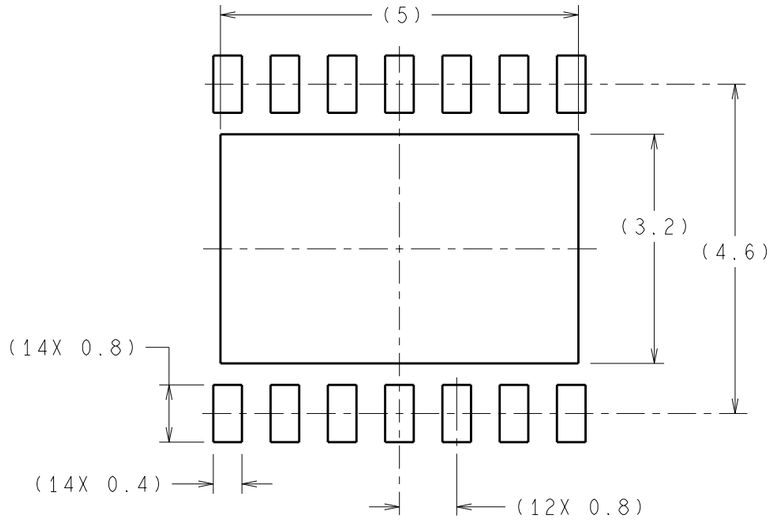
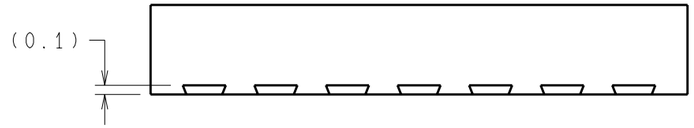
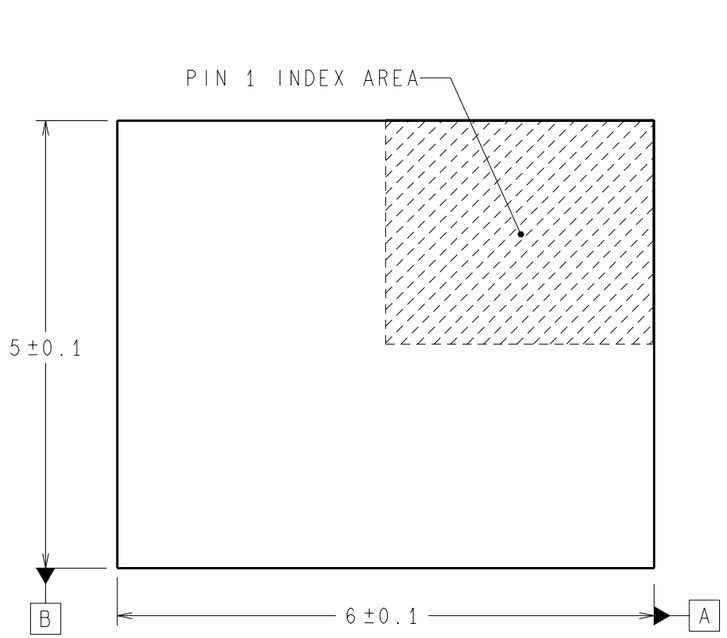
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1064	07/02/2003	LMK/MS/SN

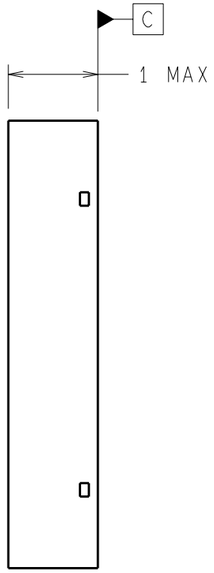


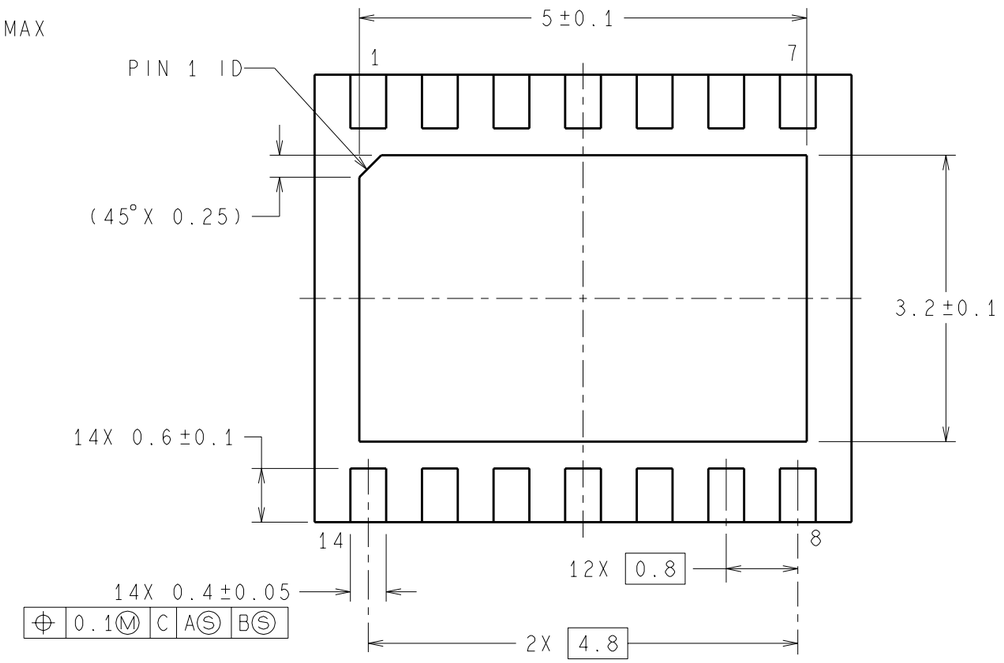
RECOMMENDED LAND PATTERN

DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN ( ) FOR REFERENCE ONLY









NOTES: UNLESS OTHERWISE SPECIFIED.

1. FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. MAXIMUM ALLOWABLE METAL BURR ON LEAD TIPS AT THE PACKAGE EDGES IS 76 MICRONS.
3. NO JEDEC REGISTRATION AS OF JULY 2003.

APPROVALS	DATE
DRAWN: LYE MENG KONG	07/02/2003
DFTG. CHK.: THANH LEQUANG	07/02/2003
ENGR. CHK.: N. SANTHIRAN	07/02/2003

PROJECTION: MM

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

LLP, PLASTIC, DUAL, 6x5x1mm BODY, 14 LD, 0.8mm PITCH, NO PULLBACK

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-SRC14A	A

FORMERLY: N/A

SHEET 1 of 1